ASSOCIATION CONNE	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute									Materia	als and Mf	g Informa	ation	
Supplier Info	rmation						·								
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2024-04-29			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-St	ewards	Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com				
uthorized Repr	resentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-St	ewards	Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com				
Requ	ester Item Number	Item Number Mfr Item Number Mfr Item Name NC7WZ17L6X- L22175 UHS 2 Buffer Sc		m Number Mfr Item Name			Effective Dat	e Versio	on l	Manufacturing Site		W	eight*	UOM	Unit Type
				chmitt		2024-04-29 TH2			2.115		mg	Each			
Ianufacturii	ng Proccess Informati	on						·						·	
Termi	nal Plating / Grid Array Mat	Plating / Grid Array Material		Terminal Base Alloy		STD-020 MSL Rating		Peak Process Body Temperature		re Max Time at Peak Temper		Temperatu	ature Number of Reflow Cycles		eles
Precio Sn)			CU Alloy 1		1		260		С	30 seco		second	s 3		
Comments									·						
vel 1 - maximu	m time at peak temperatur	e during so	ldering is 10-3	30 seconds											
	nation regarding material c														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply the interest of the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.056	mg	Supplier	Silicon (Si)	7440-21-3		0.056	mg
Die Attach Epoxy	0.003	mg		Epoxy resin	proprietary data		0.0019	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.001	mg
Lead Frame	0.803		Supplier	Magnesium (Mg)	7439-95-4		0.001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0063	mg
			В	Nickel (Ni)	7440-02-0		0.0261	mg
			Supplier	Copper (Cu)	7440-50-8		0.7696	mg
Mold Compound-Black	1.204		Supplier	Carbon Black (C)	1333-86-4		0.006	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.0595	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.0783	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0602	mg
Plating	0.025		Supplier	Silver (Ag)	7440-22-4		0.0001	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			В	Nickel (Ni)	7440-02-0		0.0247	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.024	mg	Supplier	Gold (Au)	7440-57-5		0.024	mg